

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7777381

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
PING-WEI WANG	12/11/2020
CHIH-CHUAN YANG	12/11/2020
LIEN JUNG HUNG	12/11/2020
FENG-MING CHANG	12/11/2020
KUO-HSIU HSU	12/11/2020
KIAN-LONG LIM	12/11/2020
RUEY-WEN CHANG	12/11/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
<b>Street Address:</b>	8, LI-HSIN RD. 6
<b>Internal Address:</b>	HSINCHU SCIENCE PARK
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-78
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	18151991
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>ATTORNEY DOCKET NUMBER:</b>	20200263/24061.4168US02
<b>NAME OF SUBMITTER:</b>	MARTHA ROBINSON
<b>SIGNATURE:</b>	/MARTHA ROBINSON/

PATENT

<b>DATE SIGNED:</b>	02/03/2023
<b>Total Attachments: 3</b> source=24061.4168US02 - Assignment#page1.tif source=24061.4168US02 - Assignment#page2.tif source=24061.4168US02 - Assignment#page3.tif	

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Docket No.: 20200263 / 24061.4168US01  
Customer No.: 000042717**ASSIGNMENT**

WHEREAS, we,

- |     |                 |    |                                 |
|-----|-----------------|----|---------------------------------|
| (1) | Ping-Wei Wang   | of | Hsinchu, Taiwan (R.O.C.)        |
| (2) | Chih-Chuan Yang | of | Hsinchu, Taiwan (R.O.C.)        |
| (3) | Lien Jung Hung  | of | Taipei, Taiwan (R.O.C.)         |
| (4) | Feng-Ming Chang | of | Hsinchu County, Taiwan (R.O.C.) |
| (5) | Kuo-Hsiu Hsu    | of | Taoyuan County, Taiwan (R.O.C.) |
| (6) | Kian-Long Lim   | of | Hsinchu City, Taiwan (R.O.C.)   |
| (7) | Ruey-Wen Chang  | of | Hsinchu, Taiwan (R.O.C.)        |

have invented certain improvements in

**SHARED BIT LINES FOR MEMORY CELLS**

for which we have executed an application for Letters Patent of the United States of America,

  X   of even date filed herewith; and           filed on                      and assigned application number                     ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, **TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD., ("TSMC"), 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan, Republic of China** is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America,

whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ping-Wei Wang

Dated: 12/11/20

Ping-Wei Wang  
Inventor Signature

Inventor Name: Chih-Chuan Yang

Dated: 2020/12/11

Chih-Chuan Yang  
Inventor Signature

Inventor Name: Lien Jung Hung

Dated: 2020/12/11

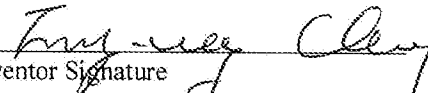
Lien-Jung Hung  
Inventor Signature

Docket No.: 20200263 / 24061.4168US01  
Customer No.: 000042717

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Inventor Name: Feng-Ming Chang

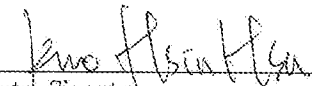
Dated: 2020.12.11

  
Inventor Signature

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Inventor Name: Kuo-Hsiu Hsu


Dated: 2020.12.11

  
Inventor Signature

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Inventor Name: Kian-Long Lim

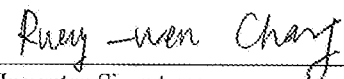
Dated: 2020 Dec 11

  
Inventor Signature

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Inventor Name: Ruey-Wen Chang

Dated: 2020.12.11

  
Inventor Signature